

**Description**

The SX3P06MI uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a

Battery protection or in other Switching application.

**General Features**

$V_{DS} = -60V$   $I_D = -3.8A$

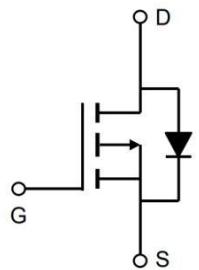
$R_{DS(ON)} < -150m\Omega$  @  $V_{GS} = -10V$

**Application**

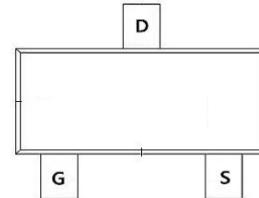
Battery protection

Load switch

Uninterruptible power supply



SOT-23-3L

**Absolute Maximum Ratings ( $T_c = 25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-3.8	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-2.4	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-12	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>3</sup>	1.5	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	125	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	80	°C/W

**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-60	-67	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=-1\text{mA}$	---	-0.021	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-1.5\text{A}$	---	125	150	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-1\text{A}$	---	158	200	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-1.0	1.7	-2.5	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	4.08	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=-48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$ , $I_{\text{D}}=-1.5\text{A}$	---	5.9	---	S
$Q_g$	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-20\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-1.5\text{A}$	---	4.6	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	1.4	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	1.62	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_{\text{G}}=3.3\Omega$ , $I_{\text{D}}=-1\text{A}$	---	17.4	---	ns
$T_r$	Rise Time		---	5.4	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	37.2	---	
$T_f$	Fall Time		---	2.4	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	531	---	pF
$C_{\text{oss}}$	Output Capacitance		---	59	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	38	---	
$I_s$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-1.7	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,4</sup>		---	---	-7	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_{\text{S}}=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.2	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

## Typical Characteristics

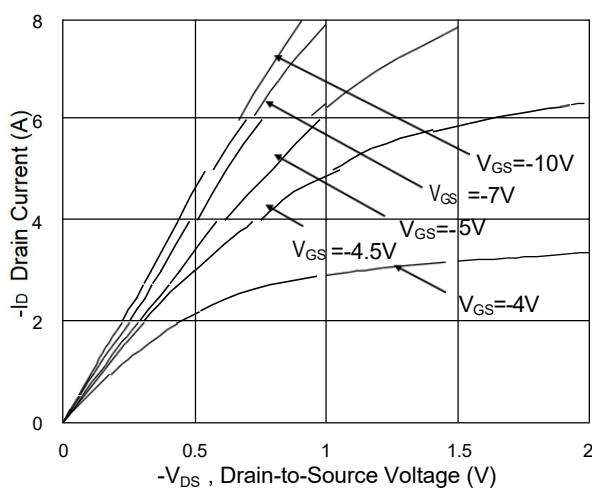


Fig.1 Typical Output Characteristics

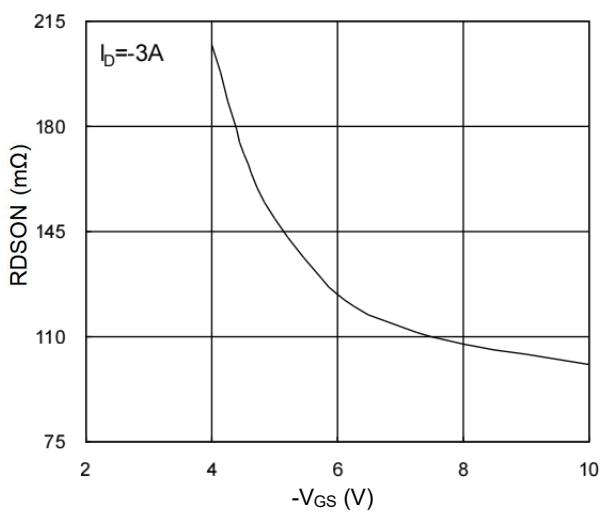


Fig.2 On-Resistance vs. G-S Voltage

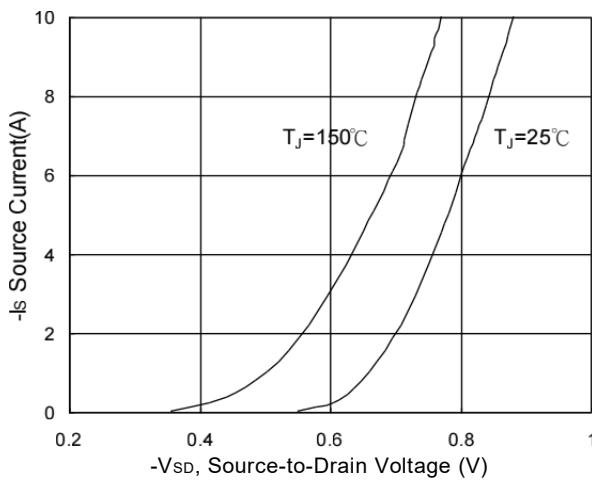


Fig.3 Forward Characteristics Of Reverse

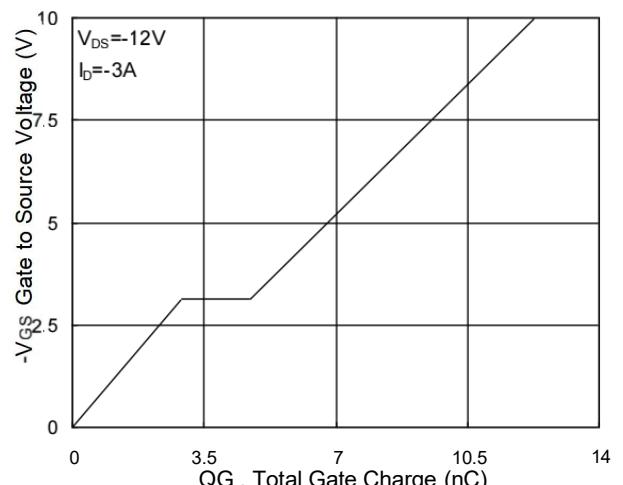


Fig.4 Gate-Charge Characteristics

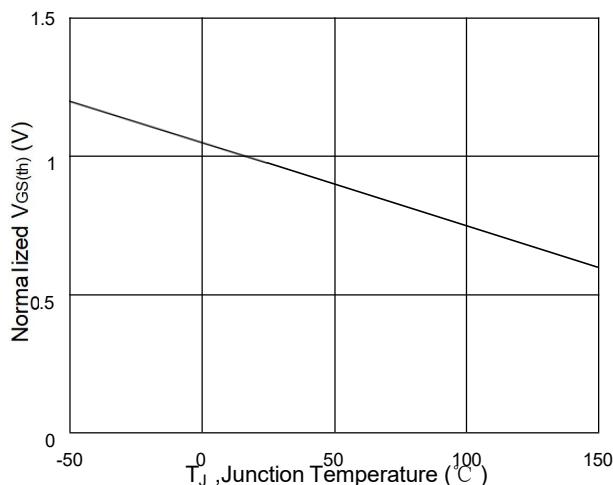


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

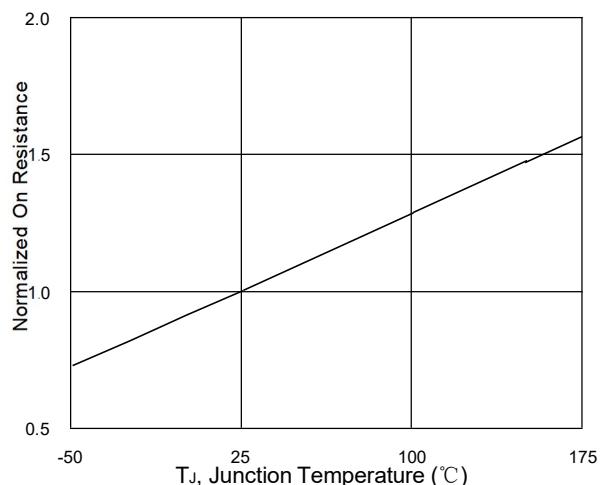
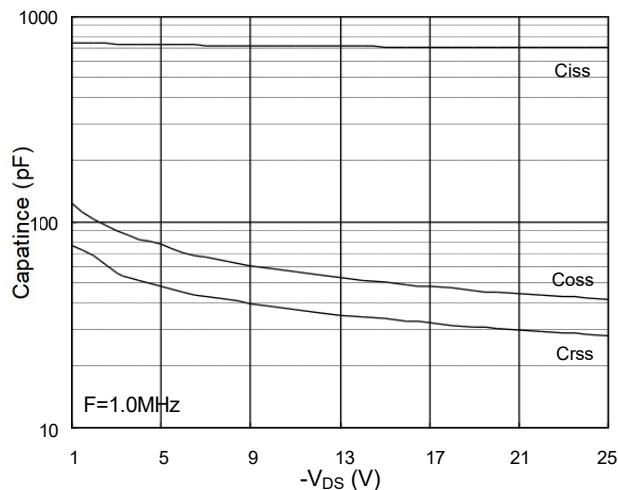
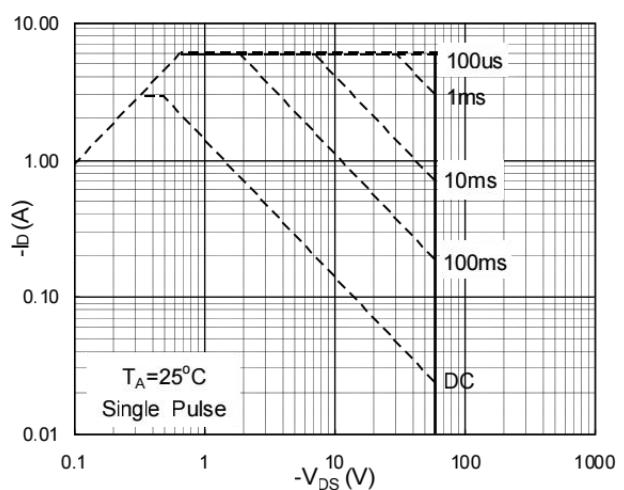


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

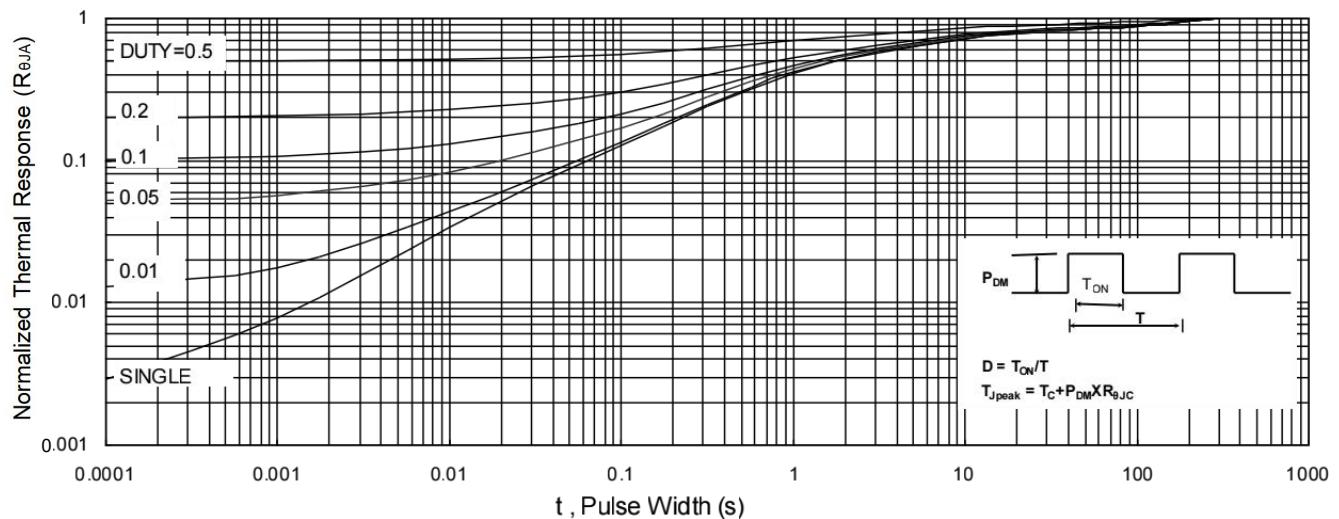
## Typical Characteristics



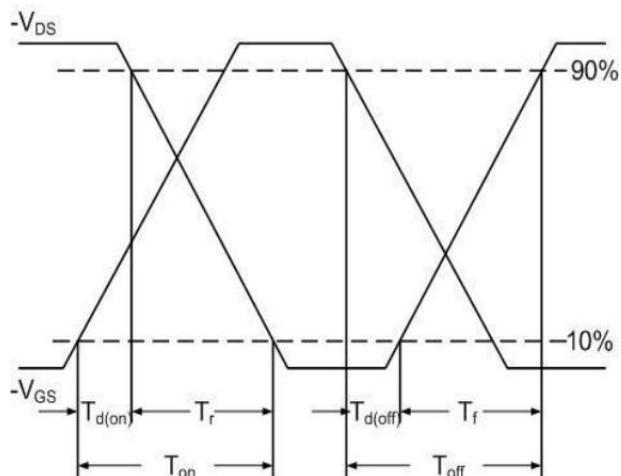
**Fig.7 Capacitance**



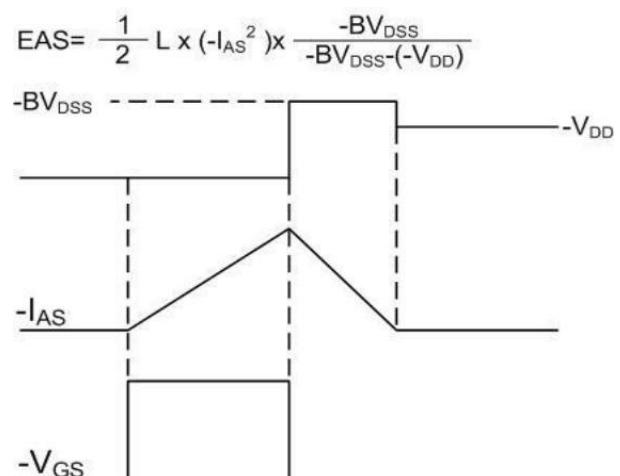
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

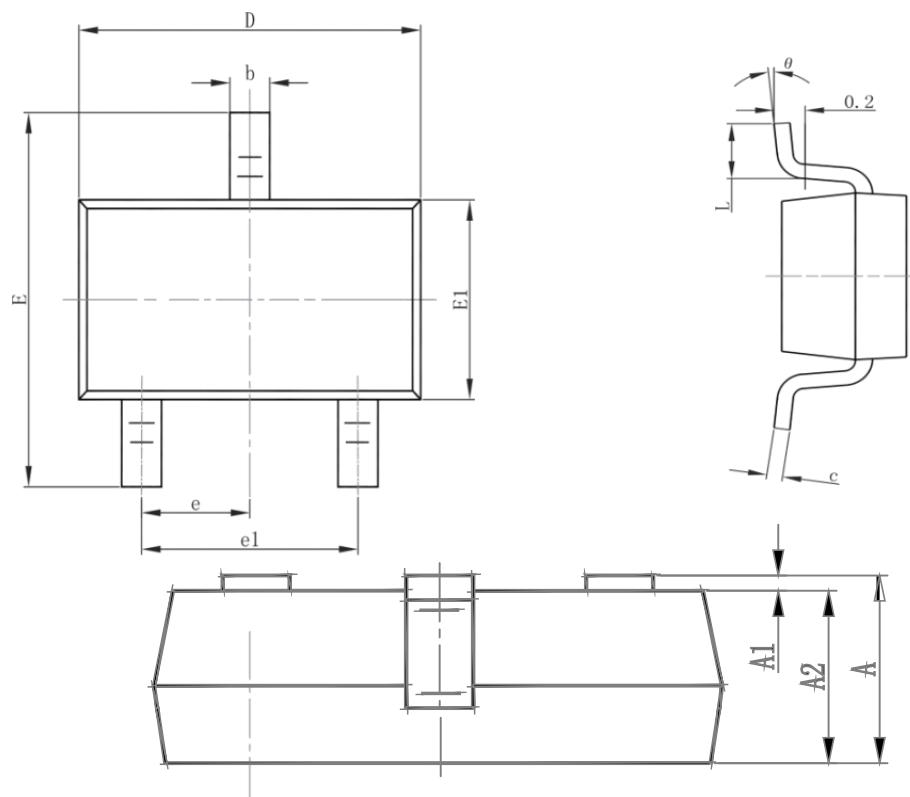


**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**

## MOSFET Package Mechanical Data-SOT23-3



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	SOT23-3L		3000